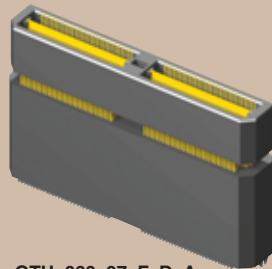


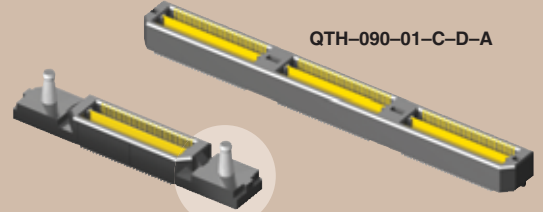


(0,50mm) .0197"

QTH SERIES



QTH-060-07-F-D-A



QTH-090-01-C-D-A

QTH-030-01-L-D-A-RT1

HIGH SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTH

Insulator Material:

Liquid Crystal Polymer



Terminal Material:

Phosphor Bronze



Plating:

Au or Sn over 50µ" (1,27µm) Ni

Current Rating:

Contact: 1.0A @ 30°C

Temperature Rise

Ground Plane: 7.8A @ 30°C

Temperature Rise

Operating Temp Range:

-55°C to +125°C

Voltage Rating:

125 VAC (5mm Stack Height)

Max Cycles:

100

Unmating Force (-RT1 option):

-RT1 option increases unmating force up to 50%

RoHS Compliant:

Yes

Processing:

Max Processing Temp:

230°C for 60 seconds, or

260°C for 20 seconds 3x

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10mm) .004" max (030-060)

(0,15mm) .006" max (090-120)

Board Stacking:

For applications requiring more than two connectors per board or 4 banks or more, contact ipg@samtec.com

APPLICATION SPECIFIC OPTION

- 14mm, 15mm, 22mm and 30mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
 - 30µ" (0,76µm) Gold (Specify -H plating for Data Rate cable mating applications.)
 - Edge Mount & Guide Posts
 - 150 positions per row
- Call Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

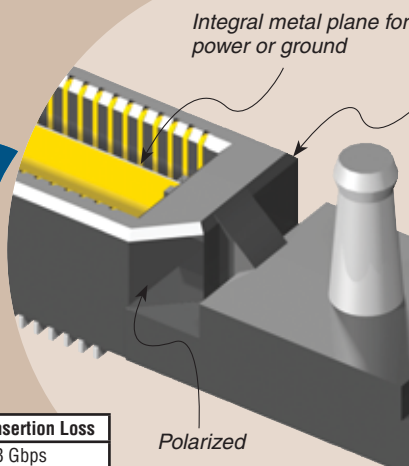
Board Mates:
QSH

Cable Mates:
HFHM2, HQCD, HQDP
(See Application Specific note)



5mm Stack Height	Type	Rated @ -3dB Insertion Loss
Single-Ended Signaling	-D	9 GHz / 18 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps
Differential Pair Signaling	-DP	9.5 GHz / 19 Gbps

Performance data for other stack heights and complete test data available at www.samtec.com?QTH or contact sig@samtec.com



Standard Stack Heights from 5mm to 25mm



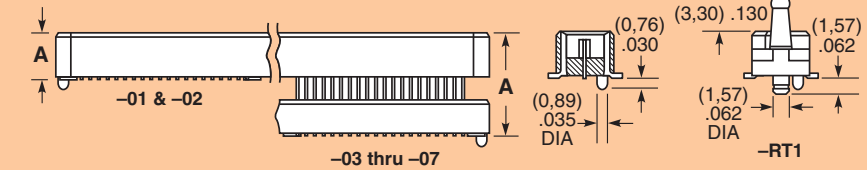
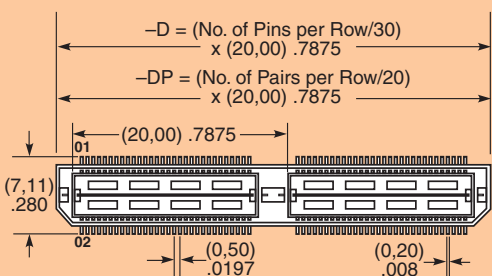
Protocols Supported

Hypertransport™
XAUI
PCI Express®
SATA
Infiniband

Download app notes at www.samtec.com/appnote
Contact SIG @ samtec.com for questions on protocols

ALSO AVAILABLE
Board Spacing Standoffs. See SO Series.

QTH	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-030, -060, -090, -120 (60 total pins per bank = -D)	Specify LEAD STYLE from chart	-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails -L = 10µ" (0,25µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails -C* = Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails	-D = Single-Ended -D-DP = Differential Pair (-01 only)		-K = (7,00mm) .275" DIA Polyimide film Pick & Place Pad (N/A with -05 & -07 lead style) -TR = Tape & Reel (-090 positions maximum) -RT1 = Retention Option (-01 Lead Style only & -090 positions maximum)



QTH LEAD STYLE	A	HEIGHT WITH QSH
-01	(4,27) .168	(5,00) .197
-02	(7,26) .286	(8,00) .315
-03	(10,27) .404	(11,00) .433
-04	(15,25) .600	(16,00) .630
-05	(18,26) .718	(19,00) .748
-07	(24,24) .954	(25,00) .984

Processing conditions will affect mated height.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM